



RELIABILITY REPORT  
FOR  
MAX17575ATC+T  
PLASTIC ENCAPSULATED DEVICES

April 13, 2017

**MAXIM INTEGRATED**

160 RIO ROBLES  
SAN JOSE, CA 95134

 Eric Wright Reliability Engineer	 Brian Standley Manager, Reliability
--	--

## Conclusion

The MAX17575ATC+T successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

## Table of Contents

<b>I. ....Device Description</b>	<b>IV..... Die Information</b>
<b>II. ....Manufacturing Information</b>	<b>V..... Quality Assurance Information</b>
<b>III. ....Packaging Information</b>	<b>VI..... Reliability Evaluation</b>
<b>.....Attachments</b>	

### I. Device Description

#### A. General

The MAX17575 high-efficiency, high-voltage, synchronous step-down DC-DC converter with integrated MOSFETs operates over a 4.5V to 60V input. The converter can deliver up to 1.5A and generates output voltages from 0.9V up to  $0.9 \times V_{IN}$ . The feedback (FB) voltage is accurate to within  $\pm 1.2\%$  over  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ . The MAX17575 uses peak current-mode control. The device is available in a 12-pin (3mm x 3mm) TDFN package. Simulation models are available.

## II. Manufacturing Information

A. Description/Function:	4.5V–60V, 1.5A, High-Efficiency, Synchronous Step-Down DC-DC Converter with Internal Compensation
B. Process:	S18
C. Fabrication Location:	USA
D. Assembly Location:	Taiwan, Thailand
E. Date of Initial Production:	April 7, 2017

## III. Packaging Information

A. Package Type:	12-pin TDFN
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Bondwire:	CuPd (1.3 mil dia.)
E. Mold Material:	Epoxy with silica filler
F. Assembly Diagram:	#05-100256
G. Flammability Rating:	Class UL94-V0
H. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
I. Single Layer Theta Ja:	63°C/W
J. Single Layer Theta Jc:	8.5°C/W
K. Multi Layer Theta Ja:	41°C/W
L. Multi Layer Theta Jc:	8.5°C/W

## IV. Die Information

A. Dimensions:	66.9291X95.6693 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Minimum Metal Width:	0.23 microns (as drawn)
E. Minimum Metal Spacing:	0.23 microns (as drawn)
F. Isolation Dielectric:	SiO <sub>2</sub>
G. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

- A. Quality Assurance Contacts: Eric Wright (Reliability Engineering)  
Brian Standley (Manager, Reliability)  
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% for all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 80 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 13.7 \times 10^{-9}$$

$$\lambda = 13.7 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maximintegrated.com/qa/reliability/monitor>. Cumulative monitor data for the S18 Process results in a FIT Rate of 0.40 @ 25C and 6.96 @ 55C (0.8 eV, 60% UCL)

### B. E.S.D. and Latch-Up Testing

The PI42-0 die type has been found to have all pins able to withstand an HBM transient pulse of +/-2500V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250mA and overvoltage per JEDEC JESD78.

**Table 1**  
Reliability Evaluation Test Results

**MAX17575ATC+T**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
<b>Static Life Test</b> (Note 1)	Ta = 135C Biased Time = 192 hrs.	DC Parameters & functionality	80	0	

Note 1: Life Test Data may represent plastic DIP qualification lots.